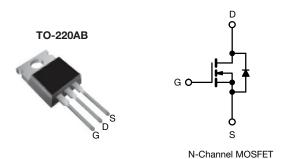




# **Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	600			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 10 V	4.4		
Q <sub>g</sub> max. (nC)	18			
Q <sub>gs</sub> (nC)	3.0			
Q <sub>gd</sub> (nC)	8.9			
Configuration	Single			

#### **FEATURES**

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

#### **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRFBC20PbF		
Lead (Pb)-free and halogen-free	IRFBC20PbF-BE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	600	V	
Gate-source voltage			$V_{GS}$	± 20		
Continuous drain current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C		2.2	А	
		T <sub>C</sub> = 100 °C	I <sub>D</sub>	1.4		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	8.0		
Linear derating factor				0.40	W/°C	
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	84	mJ	
Repetitive avalanche current <sup>a</sup>			I <sub>AR</sub>	2.2	Α	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	5.0	mJ	
Maximum power dissipation	T <sub>C</sub> = 25 °C		P <sub>D</sub>	50	W	
Peak diode recovery dV/dt <sup>c</sup>			dV/dt	3.0	V/ns	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering recommendations (peak temperature) <sup>d</sup>	For	10 s	300		$\neg$	
Maunting towns	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque				1.1	N⋅m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 31 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 2.2 A (see fig. 12)
- c.  $I_{SD} \le 2.2 \text{ A}$ ,  $dI/dt \le 40 \text{ A/}\mu\text{s}$ ,  $V_{DD} \le V_{DS}$ ,  $T_J \le 150 \text{ °C}$
- d. 1.6 mm from case



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62		
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	2.5		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.88	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		-	4.0	V
Gate-source leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 20 V		-	± 100	nA
Zoro goto voltago drain augrent	1	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	-	100	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 480V$	V <sub>DS</sub> = 480V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	500	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 1.3 A <sup>b</sup>	-	-	4.4	Ω
Forward transconductance	9 <sub>fs</sub>	$V_{DS} = 50 \text{ V}, I_D = 1.3 \text{ A}^{\text{ b}}$		1.4	-	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. } 5$		-	350	-	pF
Output capacitance	C <sub>oss</sub>			-	48	-	
Reverse transfer capacitance	$C_{rss}$			-	8.6	-	
Total gate charge	Qg			-	-	18	
Gate-source charge	$Q_{gs}$	$V_{GS} = 10 \text{ V}$ $I_D = 2.0 \text{ A}, V_{DS} = 360 \text{ V}$ see fig. 6 and 13 b		-	-	3.0	nC
Gate-drain charge	$Q_{gd}$			-	-	8.9	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = 300 \text{ V}, I_{D} = 2.0 \text{ A}$ $R_{g} = 18 \Omega, R_{D} = 150 \Omega$ see fig. 10 b		-	10	-	ns
Rise time	t <sub>r</sub>			-	23	-	
Turn-off delay time	t <sub>d(off)</sub>			-	30	-	
Fall time	t <sub>f</sub>			-	25	-	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		1.2	-	7.4	Ω
Internal drain inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal source inductance	L <sub>S</sub>			-	7.5	-	''''
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.2	
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	8.0	- A
Body diode voltage	V <sub>SD</sub>	$T_J = 25  ^{\circ}\text{C},  I_S = 2.2  \text{A},  V_{GS} = 0  \text{V}^{ \text{b}}$		-	-	2.0	V
Body diode reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 2.0 A,		-	290	580	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$dI/dt = 100 \text{ A/µs}^b$		-	0.67	1.3	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and L				L <sub>D</sub> )	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

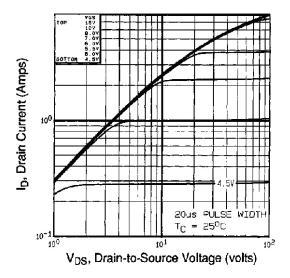


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

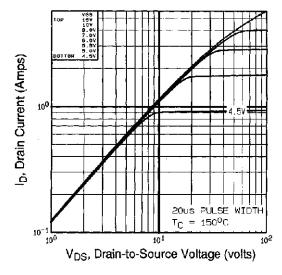


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 150 °C

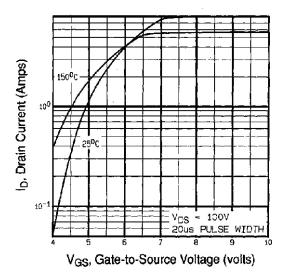


Fig. 3 - Typical Transfer Characteristics

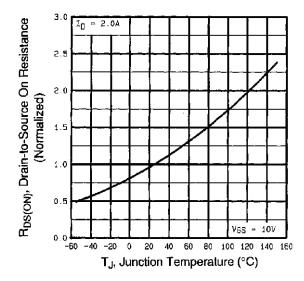


Fig. 4 - Normalized On-Resistance vs. Temperature



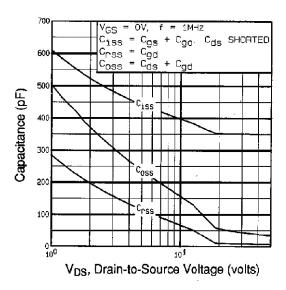


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

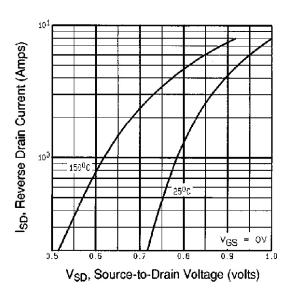


Fig. 7 - Typical Source-Drain Diode Forward Voltage

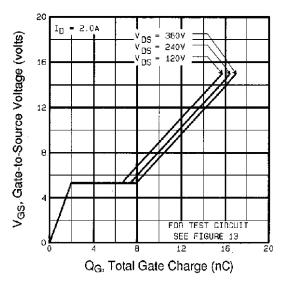


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

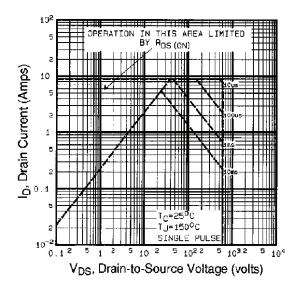


Fig. 8 - Maximum Safe Operating Area



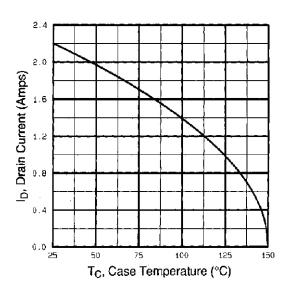


Fig. 9 - Maximum Drain Current vs. Case Temperature

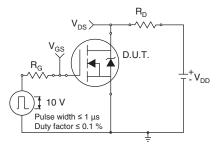


Fig. 10a - Switching Time Test Circuit

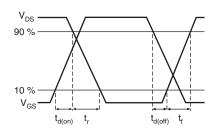


Fig. 10b - Switching Time Waveforms

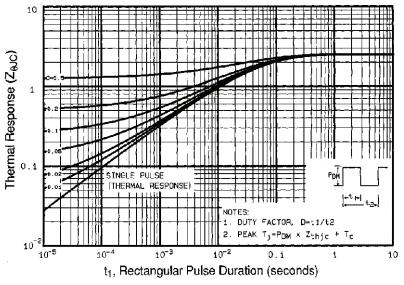


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



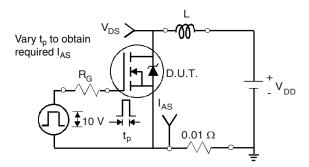


Fig. 12a - Unclamped Inductive Test Circuit

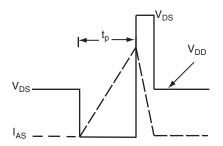


Fig. 12b - Unclamped Inductive Waveforms

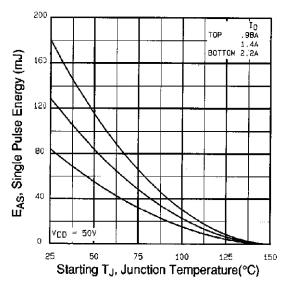


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

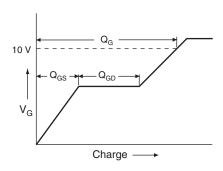


Fig. 13a - Basic Gate Charge Waveform

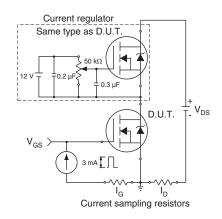
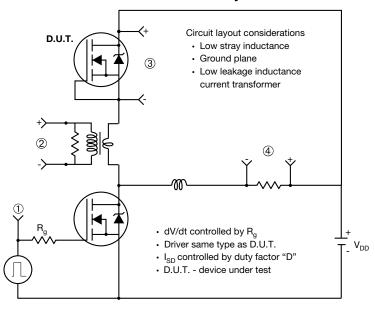


Fig. 13b - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



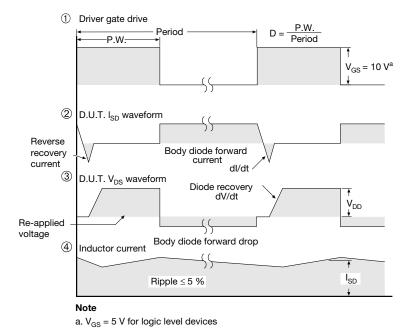


Fig. 14 - For N-Channel

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